PDFN5×6 P

P-Channel MOSFET in a PDFN5×6 Plastic Package.

V_{DS} (V) = -30V I_D =-46A (V_{GS} = ±20V)

$R_{DS(ON)}$@-10V≤12mΩ(Typ.10.5mΩ)

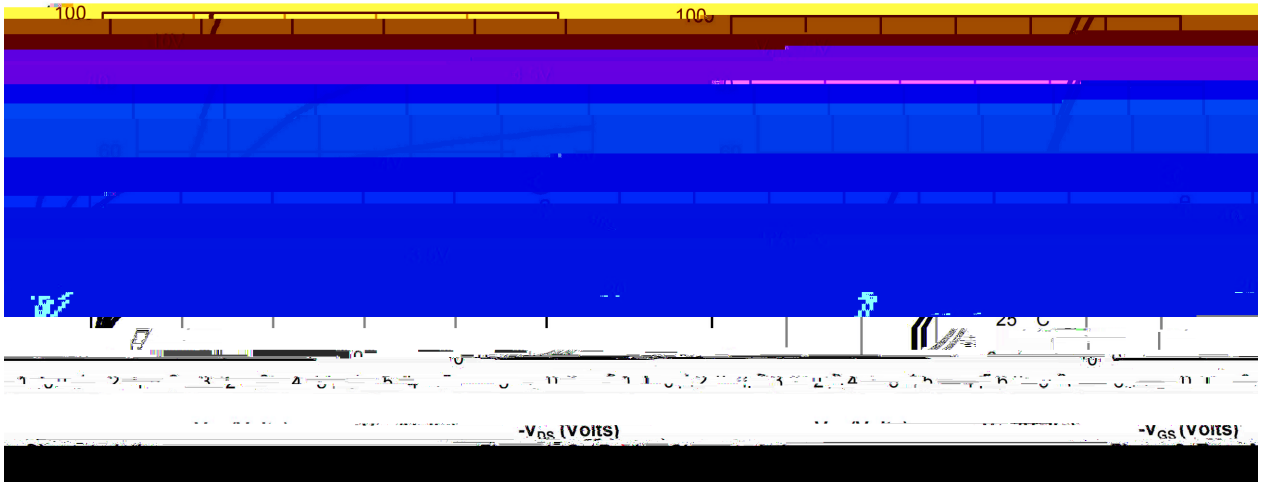
$R_{DS(ON)}$@-4.5V≤18mΩ(Typ.16.5mΩ)

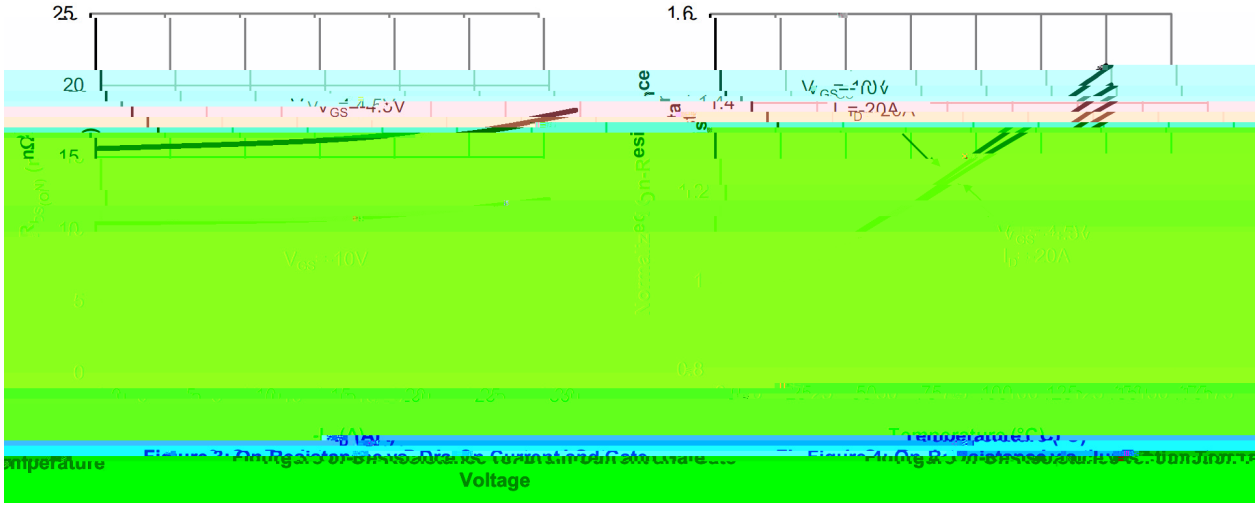
HF Product. P

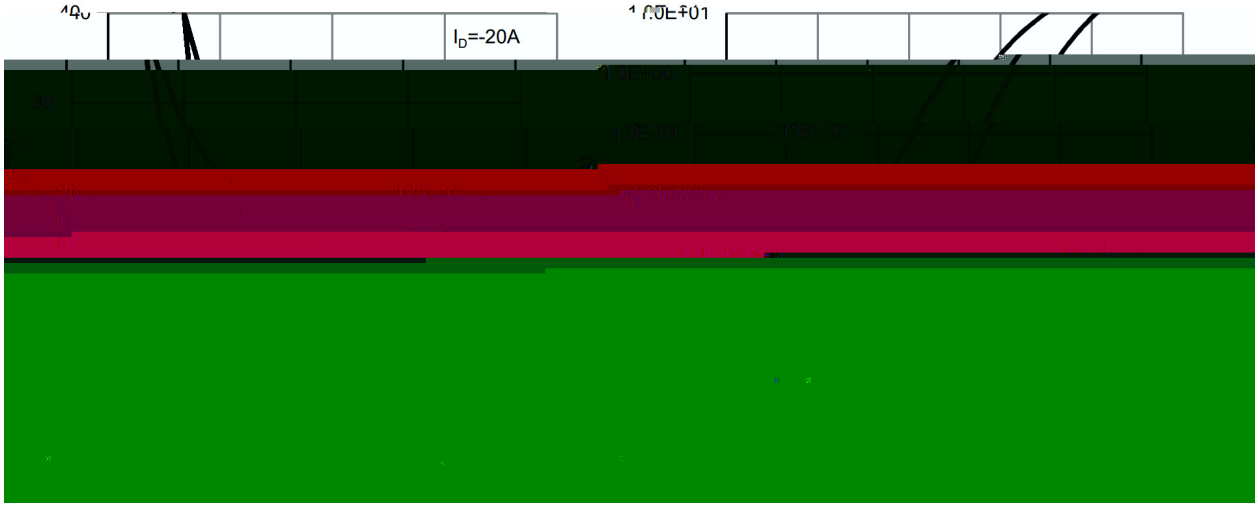
Parameter	Symbol Z.

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	I_D=-250μA V_{GS}=0V				

/ Electrical Characteristic Curve

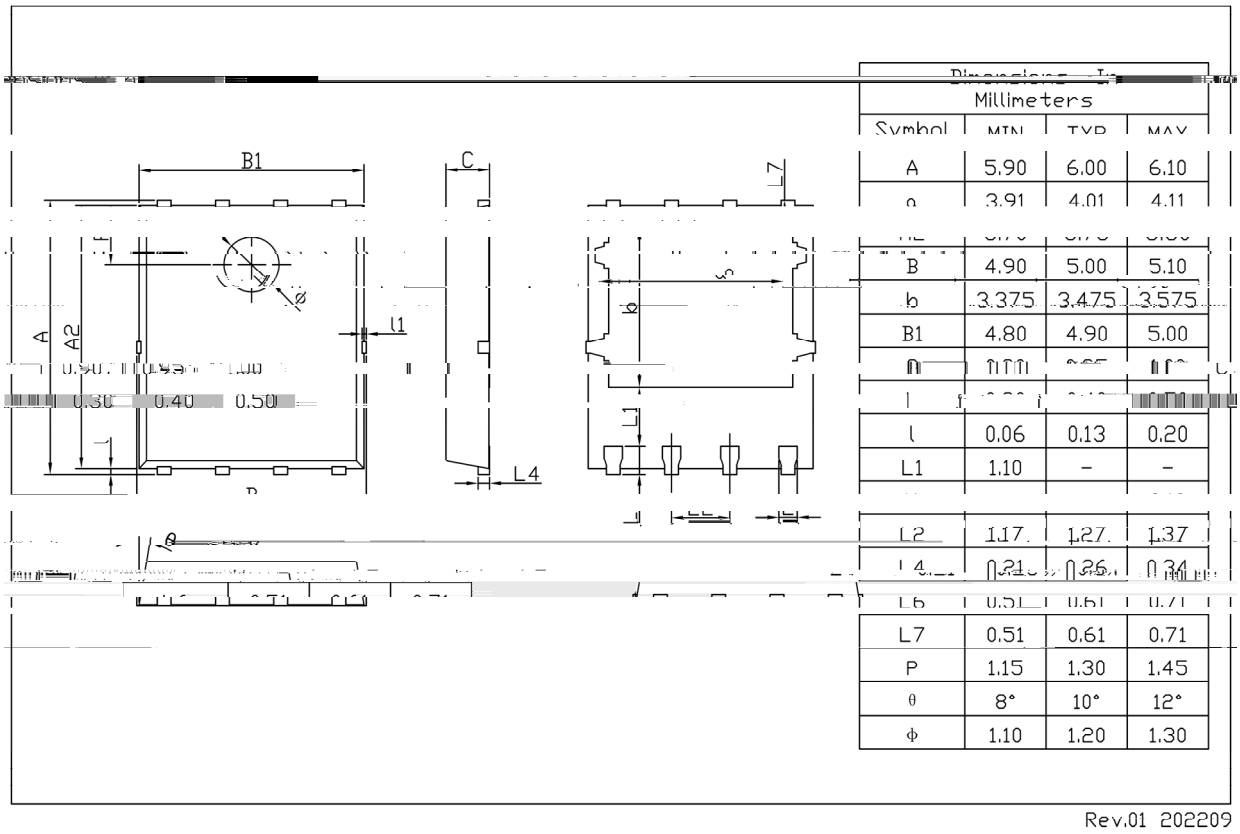






/ Package Dimensions

PDFN5×6 Unit:mm



Dimensions In Millimeters			
Symbol	MIN	TYP	MAX
A	5.90	6.00	6.10
[illegible]	3.91	4.01	4.11
B	4.90	5.00	5.10
b	3.375	3.475	3.575
B1	4.80	4.90	5.00
[illegible]	[illegible]	[illegible]	[illegible]
[illegible]	[illegible]	[illegible]	[illegible]
l	0.06	0.13	0.20
L1	1.10	–	–
[illegible]	[illegible]	[illegible]	[illegible]
L2	1.17	1.27	1.37
L4	0.21	0.26	0.34
L6	0.51	0.61	0.71
L7	0.51	0.61	0.71
P	1.15	1.30	1.45
θ	8°	10°	12°
Φ	1.10	1.20	1.30

Rev.01 202209

/ Marking Instructions



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( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)

				Note:
1	150	180	60 90sec;	1.Preheating:150~180 , Time:60~90sec.
2	245±5		5±0.5sec;	2.Peak Temp.:245±5 , Duration:5±0.5sec.
3		2 10	/sec.	3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260±5	10±1 sec.	Temp.:260±5	Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units	Dimension	(unit mm³)
	/ / / /		